



Product Change Notification

Change Notification #: 116563 - 00
Change Title: Humidity Indicator Card (HIC) Relocation & Desiccant Pouch Reduction, PCN 116563-00, Transport Media, Updating all Tape & Reel, Tray and Tube media packed component products
Date of Publication: November 2, 2018

Key Characteristics of the Change:

Transport Media

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	November 13, 2018
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Description of Change to the Customer:

Due to new industry standards regarding the packaging standards for component desiccant packed products, Intel will change the placement of the Humidity Indicator Card (HIC) used in shipping.

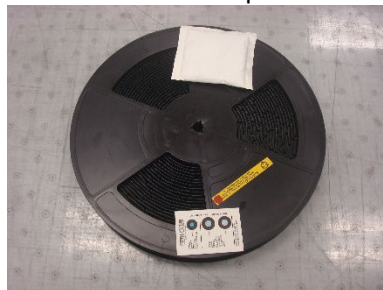
JEDEC-STD-033D insists that the HIC does not come in direct contact with the desiccant pouch. Therefore, the HIC and Desiccant pouches will be separated and moved further apart from one another as example pictures below indicate.

Pictures below are for example only. Note especially how the desiccant pouch and the humidity indicator card (HIC) will be placed at a distance from each other, at opposite ends.

Current Pack – All T&R products



New Pack – All T&R products



Current Pack – All Tube products



New Pack – All Tube products



Current Pack – All tray products
(two desiccant pouches)



New Pack – All tray products
(one desiccant pouch)



Only one
desiccant pouch
for all tray
products

Pin 1 Tray Orientation

Also, please note above that the number of desiccant pouches will decrease from two pouches per moisture barrier bag down to a single desiccant pouch per bag. This pertains exclusively to Tray packed products only. This decision results from a change announced prior to any customers receiving Tray packed products wherein the use of the corrugated cardboard shim will be replaced by a new plastic shim (also noted in the picture above). Corrugated shims contain significantly more moisture than the plastic shims and therefore, in moving to the new universal plastic shim, only one desiccant pouch will be needed. Please refer to the example pictures above.

Customer Impact of Change and Recommended Action:

There is no change to the form, fit, or function of the product. Nor is there any action required from customers other than to be aware and familiar with the changes described in this Product Change Notification.

Intel will deplete older packaged material currently on shelves during the transition and customers should expect to see a mix of packaging options until older packaged material has been depleted.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

All Intel® packed component products are affected, including Tape & Reel, Tray and Tube packed products.

PCN Revision History:

Date of Revision:

November 2, 2018

Revision Number:

00

Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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